

Technical Information

4551 Thin-Print Etchable Gold Conductor

The thick film gold composition 4551 is designed for applications requiring narrow lines and spaces, smooth pattern edges, and high electrical conductivity. It is deposited by screen printing, fired, then patterned and etched using normal photolithographic techniques. The gold particles in this paste are extremely small, allowing the deposition of very thin layers, approximately one micron per layer. As a result, the 4551 produces nearly pinhole-free films with three print-dry-fire applications. It is suitable for RF and microwave circuits. It

can also be used as termination conductor for thick film capacitors and thermistors.

Key features include:

- RoHS Compliant
- High Bulk Electrical Conductivity
- High Adhesion
- Clean Etched Area Footprint
- Accepts Gold Wire Bonds
- High Film Density
- Economical Metallization
- Compatibility with Dielectrics and Resistors

TYPICAL FIRED FILM CHARACTERISTICS⁽¹⁾

Fired Thickness 3 P/D/F	2-3 μm
Resistivity Milliohms/square at 3 μm fired thickness	≤ 10.0

(1) Typical properties are based on testing of several batches under various processing conditions. They are not intended as specification limits.

COMPOSITION PROPERTIES

Viscosity:	150 \pm 30 Kcps, when measured with Brookfield HBT viscometer, Spindle #14, utility cup, 10 RPM, 25°C
Specific Gravity:	1.8 – 2.2 g/cm ³
Recommended Thinner:	KOARTAN B-1039

RECOMMENDED PROCESSING PROCEDURE

Printing: Printing with 325 mesh stainless steel screen using 10-15 micron emulsion and 45 degree angle is recommended. Other mesh counts, 400-280, and emulsion thicknesses, 5-25 μm , may be used for special applications. Squeegee speeds of up to 10 inches/sec may be utilized.

Coverage is approximately 140 cm^2/g per layer, when utilizing a 325 mesh screen and a wet print thickness of about 30 μm .

Drying: Wet prints should be allowed to level for 5-10 minutes prior to drying. Dry for 10-15 minutes in a convection oven or belt dryer at 125°C-150°C.

Firing: Firing in air using a belt furnace and a 36-60 minute profile, with 10 minutes at a peak temperature of 850°C is recommended. Air flow rates must be optimized to ensure that the products of binder burn-off discharge properly and create a fully oxidizing atmosphere in the muffle.

Application Notes: A fired thickness of 2-3 μm and good photolithographic technique allow the etching of 1.5-2 mil lines with only minor undercutting. A 325 mesh screen with thin emulsion or a 400 mesh calendared screen may be used to obtain the desired thickness and surface morphology.

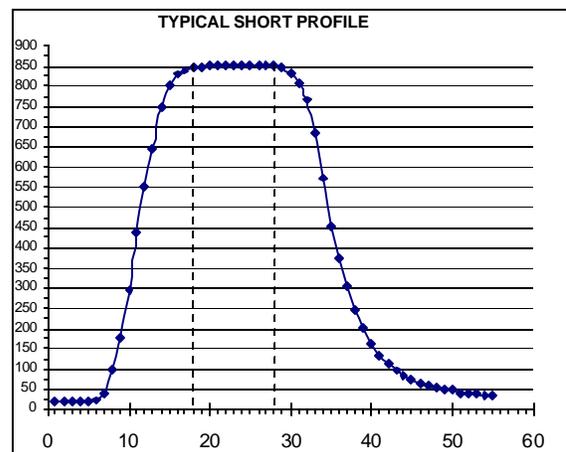
The 4551 gold has excellent adhesion to 96% and 99.5% alumina substrate.

At the recommended thickness, the surface of the fired film is hard and requires optimization of the wire bonder set up. Lower force and power settings than those used for standard thick film gold should be used.

The information presented herein is based on data believed to be dependable and is accurate and reliable to the best of our knowledge and belief, but not guaranteed to be so. Koartan Company assumes no liability arising from the use of this product or the information provided herein. It is the responsibility of the user to verify the information and to establish the suitability of the product(s) for any particular application. Nothing herein is to be construed as recommending any practice or any product in violation of any patent or in violation of any law or regulation.

The recommended steps for etching are as follows:

1. Clean fired substrates in methanol and bake at 150°C to drive off moisture.
2. Apply Shipley S1800 photoresist or equivalent at about 4000 rpm. Bake at 110°C-120°C for 1 hour.
3. Expose to UV light. Exposure time depends on source intensity, but should generally be about 30 seconds.
4. Develop using Shipley 351 developer or equivalent.
5. Rinse in distilled water and immerse in potassium iodide/iodine or especially formulated etch solution. In order to minimize undercutting, stirring or agitation of the solution is not recommended. It may, however, be heated to speed up the etching process.
6. Use Shipley 1165 or equivalent to remove photoresist from the developed pattern.



Temperature (°C) vs. Time (minutes)

Storage and Shelf Life: Store in tightly capped containers at room temperature. Shelf life is 6 months for unopened jars. Under ordinary conditions of storage and use the product should not require thinning. However, solvent loss during extended printing runs may be replaced by incorporating up to 0.5% of Koartan A-1039 thinner